			1					
Applicabl	e standard							
Operating temperature rai		nge	-35°C to +85°C(Note 1)	Stor	age perature range	-10°C to +60°C(Note 3)		
Rating	Operating humidity range		20 % to 80 % (Note 2)	Storage humidity range		40 % to 70 %(Note 3)		
	Voltage		150 V AC (DC)	Current		1 A		
	Applicable		DF13-*DS-1 25C		licable	DF13(G)-2630SCF		
Connector					tact	DF13-3032SCF		
			Specifica	tions	S			
Item		Test method			Requirements			АТ
Construc	tion				•			
General exa	General examination		Visually and by measuring instrument.			According to drawing.		
Marking	Marking		Confirmed visually.					
Electric o	haracteris	tics			1		1	
Contact resis	stance	100 m A (DC or 1000 Hz).			30 mΩ MAX.			_
Insulation re	Insulation resistance).	500 MΩ MIN.			_	
Voltage proof		500 V AC for 1 min.			No flashover or breakdown.			_
Mechani	cal charact	eristics			1			
Mechanical operation		30 times insertions and extractions.			 Contact resistance: 30 mΩ MAX. No damage, crack or looseness of parts. 			_
Vibration		Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 2 h, for 3 directions.			 No electrical discontinuity of 1μs. No damage, crack or looseness of parts. 			_
Shock		490 m/s ² duration of pulse 11 ms at 3 times for 3 directions.						_
Environn	nental char							
Rapid chang			ture -55→ 15 to 35→+85→ 15 to 35 °c		① Contact resistan	ce: 30mΩ MAX.		
temperature		Time $30 \rightarrow 2$ to $3 \rightarrow 30 \rightarrow 2$ to 3 min. Under 5 cycles.			 ② Insulation resistance: 500 MΩ MIN. ③ No damage, crack or looseness of parts. 			_
Damp heat (Steady state)		Exposed at 40 ± 2 °c, 90 to 95 %, 96 h.					Х	_
heat 2)		1) Reflow soldering ≪ Reflow area ≫ 250°C MAX 10 sec MAX 230°C MIN 60 sec MAX ≪ Preheating area ≫ 170°C to 190°C 60 sec to 120 sec Put through in reflow furnace twice, leave in ambient temperature and humidity for 1 hour. 2) Manual soldering Soldering iron temperature :300°C, Soldering time : 3sec. No strength on contact.			No deformation of case of excessive looseness of the terminals.			_
Solderability		Soldered at solder temperature,			Solder shall cover a minimum of			_

Remarks

Note 1:Include the temperature rising by current.

Note 2:No condensing

Note 3:Apply to the condition of long term storage for unused products before pcb on board,

245°c for insertion duration, 3sec.

after pcb on board, operating temperature and humidity range is applied for interim storage during transportation.

Cou	nt Description of revisions	Designed			Checked	Date
\triangle						
Unless o	herwise specifid , refer to IEC 60512.	Ар	proved	HS. OKAWA	16. 05. 16	
		Cł	necked	TS. FUKUSHIMA	16. 05. 14	
		De	signed	YK. YAMAGUCHI	16. 05. 14	
)rawn	MI. SAKIMURA	16. 05. 13
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			Drawing no.		ELC-367982-25-00	
HS.	Specification sheet		Part no.	DF13EA-*DP-1. 25V (25)		(25)
	Hirose electric co., ltd.	Code no.	CL536		1/1	

95 % of the surface being immersed.